



Description

The new 0603L Series PTC provides surface mount overcurrent protection for applications where space is at a premium and resettable protection is desired.

Features

- RoHS compliant and lead-free
- Fast response to fault currents
- Compact design saves board space
- Low resistance
- Low-profile
- Compatible with high temperature solders



Agency Approvals

AGENCY	AGENCY FILE NUMBER
	E183209
	R50119118

Applications

- USB peripherals
- Disk drives
- CD-ROMs
- Plug and play protection for motherboards and peripherals
- PDAs / digital cameras
- Game console port protection

Electrical Characteristics

Part Number	Marking	I _{hold} (A)	I _{trip} (A)	V _{max} (Vdc)	I _{max} (A)	P _{d max.} (W)	Maximum Time To Trip		Resistance		Agency Approvals	
							Current (A)	Time (Sec.)	R _{min} (Ω)	R _{1max} (Ω)		
0603L010	C	0.10	0.30	15	40	0.5	0.50	1.00	0.900	6.000	X	X
0603L020	H	0.20	0.50	9	40	0.5	1.00	0.60	0.550	3.500	X	X
0603L025	I	0.25	0.55	9	40	0.5	8.00	0.08	0.500	3.000	X	X
0603L035	F	0.35	0.75	6	40	0.5	8.00	0.10	0.200	1.000	X	X

I_{hold} = Hold current: maximum current device will pass without tripping in 20°C still air.

I_{trip} = Trip current: minimum current at which the device will trip in 20°C still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

P_d = Power dissipated from device when in the tripped state at 20°C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

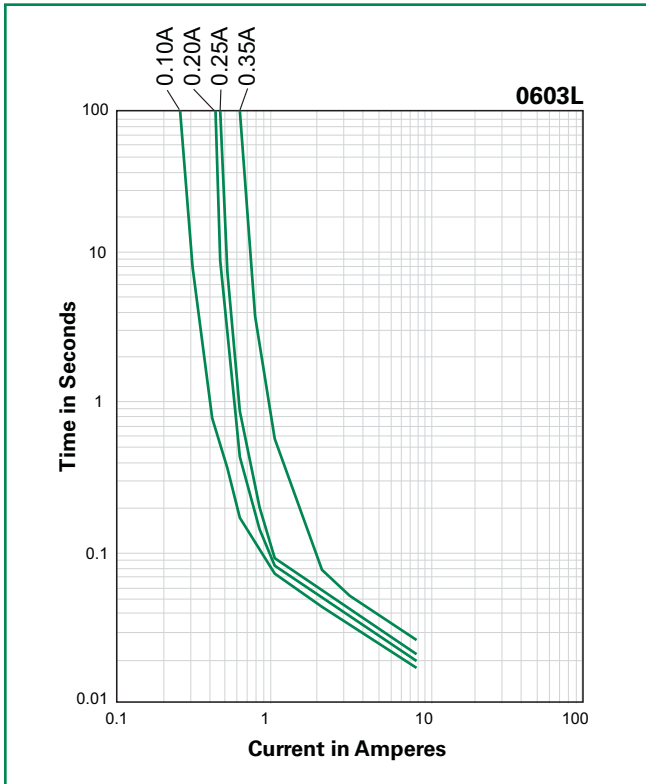
R_{1max} = Maximum resistance of device at 20°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

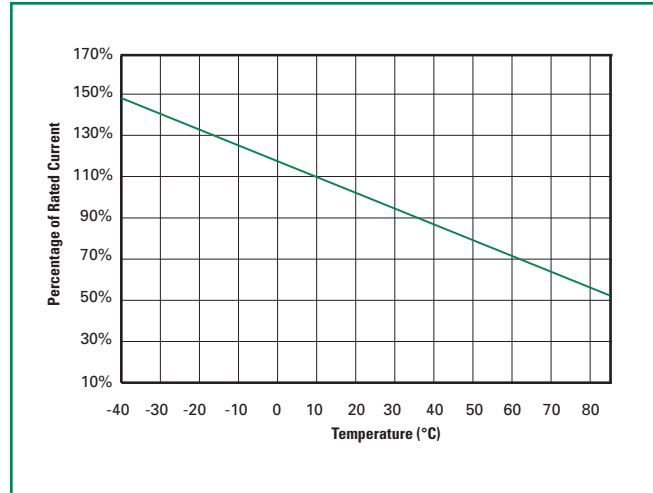
Temperature Derating

Part Number	Ambient Operation Temperature								
	-40°C	-20°C	0°C	23°C	40°C	50°C	60°C	70°C	85°C
0603L010	0.13	0.12	0.11	0.10	0.08	0.07	0.06	0.05	0.03
0603L020	0.27	0.25	0.23	0.20	0.17	0.14	0.12	0.10	0.07
0603L025	0.32	0.29	0.27	0.25	0.21	0.18	0.16	0.14	0.10
0603L035	0.47	0.41	0.38	0.35	0.29	0.26	0.24	0.20	0.14

Average Time Current Curves



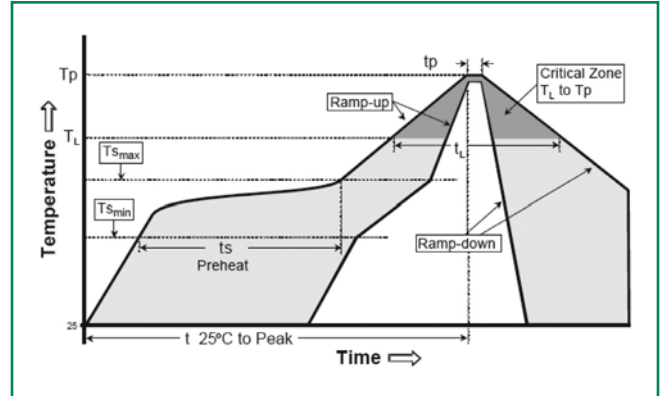
Temperature Derating Curve



The average time current curves and Temperature Derating curve performance is affected by a number of variables, and these curves provided as guidance only. Customer must verify the performance in their application.

Soldering Parameters

Profile Feature		Pb-Free Assembly
Average Ramp-Up Rate ($T_{s(max)}$ to T_p)		3°C/second max
Pre Heat:	Temperature Min ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (Min to Max) (t_s)	60 – 180 secs
Time Maintained Above:	Temperature (T_L)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak / Classification Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.



- All temperature refer to topside of the package, measured on the package body surface
- If reflow temperature exceeds the recommended profile, devices may not meet the performance requirements
- Recommended reflow methods: IR, vapor phase oven, hot air oven, N₂ environment for lead
- Recommended maximum paste thickness is 0.25mm (0.010inch)
- Devices can be cleaned using standard industry methods and solvents
- Devices can be reworked using the standard industry practices

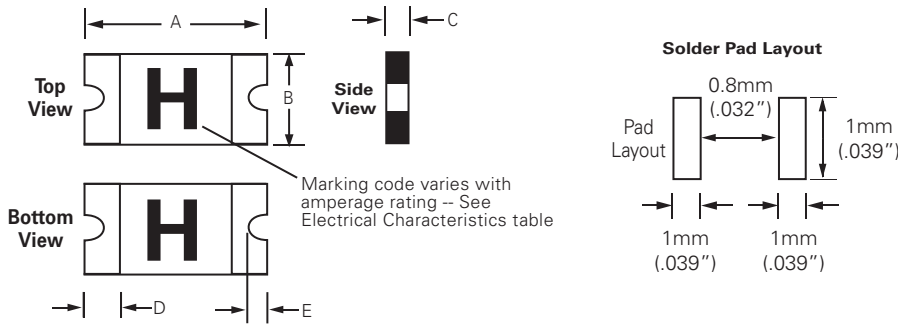
Physical Specifications

Terminal Material	Solder-Plated Copper (Solder Material: Matte Tin (Sn))
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002, Category 3.

Environmental Specifications

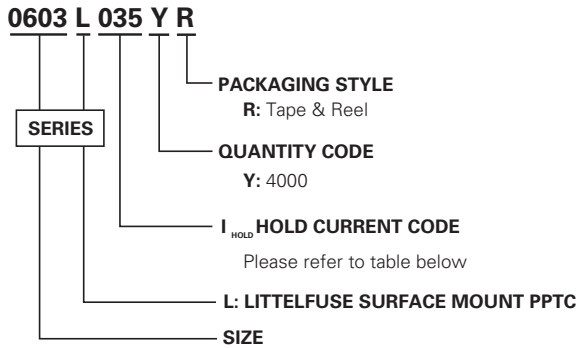
Operating/Storage Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85°C, 1000 hours -/+10% typical resistance change
Humidity Aging	+85°C, 85% R.H., 100 hours -/+15% typical resistance change
Thermal Shock	MIL-STD-202, Method 107G +85°C/-40°C 20 times -30% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215 No change
Vibration	MIL-STD-883C, Method 2007.1, Condition A No change
Moisture Sensitivity Level	Level 2, J-STD-020C

Dimensions



Part Number	A		B		C		D		E											
	Inch	mm	Inch	mm	Inch	mm	Inch	mm	Inch	mm										
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max										
0603L010	.055	.071	1.40	1.80	.024	.039	0.60	1.00	.016	.030	0.40	0.75	.006	.020	0.15	0.50	.004	.016	0.10	0.40
0603L020	.055	.071	1.40	1.80	.024	.039	0.60	1.00	.016	.030	0.40	0.75	.006	.020	0.15	0.50	.004	.016	0.10	0.40
0603L025	.055	.071	1.40	1.80	.024	.039	0.60	1.00	.016	.030	0.40	0.75	.006	.020	0.15	0.50	.004	.016	0.10	0.40
0603L035	.055	.071	1.40	1.80	.024	.039	0.60	1.00	.030	.061	0.75	1.55	.006	.020	0.15	0.50	.004	.016	0.10	0.40

Part Ordering Number System



Packaging

Part Number	Ordering Number	I_{hold} (A)	I_{hold} Code	Packaging Option	Quantity	Quantity & Packaging Codes
0603L010	0603L010YR	0.10	010	Tape and Reel	4000	YR
0603L020	0603L020YR	0.20	020	Tape and Reel	4000	YR
0603L025	0603L025YR	0.25	025	Tape and Reel	4000	YR
0603L035	0603L035YR	0.35	035	Tape and Reel	4000	YR

Tape and Reel Specifications

TAPE SPECIFICATIONS: EIA-481-1 (mm)		
	0603L010 0603L020 0603L025	0603L035
W	8.0+/- 0.30	8.0+/- 0.30
F	3.5+/- 0.05	3.5+/- 0.05
E₁	1.75+/- 0.10	1.75+/- 0.10
D₀	1.55+/- 0.05	1.55+/- 0.05
D₁	0.5(min)	0.5 (min)
P₀	4.0+/- 0.10	4.0+/- 0.10
P₁	4.0+/- 0.10	4.0+/- 0.10
P₂	2.0+/- 0.05	2.0+/- 0.05
A₀	1.10+/- 0.10	1.10+/- 0.10
B₀	1.92+/- 0.10	1.92+/- 0.10
T	0.20+/- 0.10	0.20+/- 0.10
K₀	0.72+/- 0.10	0.96+/- 0.10
Leader min.	390	390
Trailer min.	160	160

REEL DIMENSIONS: EIA-481-1 (mm)	
H	12.0+/- 0.05
W	9.0+/- 0.5
D	Ø60+0.5
F	Ø13.0 +/- 0.2
C	Ø178 +/- 1.0
H₁	11+/- 0.5
W₁	2.2+/- 0.5
W₂	3.0+0.5
W₃	4.0+0.5
W₄	5.5+0.5

0603L Series

Tape and Reel Diagram

